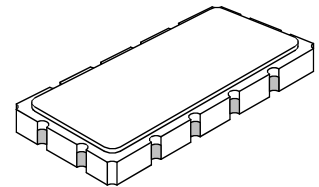


**SF2310A**

**70 MHz  
SAW Filter**



**SM13365**

- Precision IF SAW Filter
- Hermetic 13.3 x 6.5 mm Surface-mount Case
- Complies with Directive 2002/95/EC (RoHS)
- Moisture Sensitivity Level: 1

**Absolute Maximum Ratings**

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Maximum DC Voltage on any Non-ground Terminal	10	VDC
Operating Temperature Range of Component	-30 to +80	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260 °C for 30 s	

**Electrical Characteristics, 25 °C**

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	$f_C$		69.8	70.0	70.2	MHz
1 dB Bandwidth	$BW_1$			11.77		
3 dB Bandwidth	$BW_3$			12.77		
40 dB Bandwidth	$BW_{40}$			16.00	18.25	
Minimum Insertion Loss	$IL_{MIN}$			11.5	13.0	dB
Amplitude Ripple, $f_C \pm 5.0$ MHz				0.46	1.00	dB <sub>p-p</sub>
Group Delay Ripple, $f_C \pm 5.0$ MHz				30	90	ns <sub>p-p</sub>
Triple Transit Suppression			40	49		
Phase Linearity, $f_C \pm 5.0$ MHz				5	11	deg <sub>p-p</sub>
Attenuation Referenced to $IL_{MIN}$ :						dB
( $f_C - 30$ ) to ( $f_C - 15$ ) MHz			36	53		
( $f_C + 15$ ) to ( $f_C + 30$ ) MHz			36	53		
Frequency Temperature Coefficient				-94		ppm/°C

Impedance Matching to 50 $\Omega$ Unbalanced Source/Load	External L-C
Case Style	13.3 x 6.5 mm Nominal Footprint
Lid Symbolization (YY = year, WW = week, S = Shift, ## = Sequence Code)	RFM/SF2310A/YYWWS##

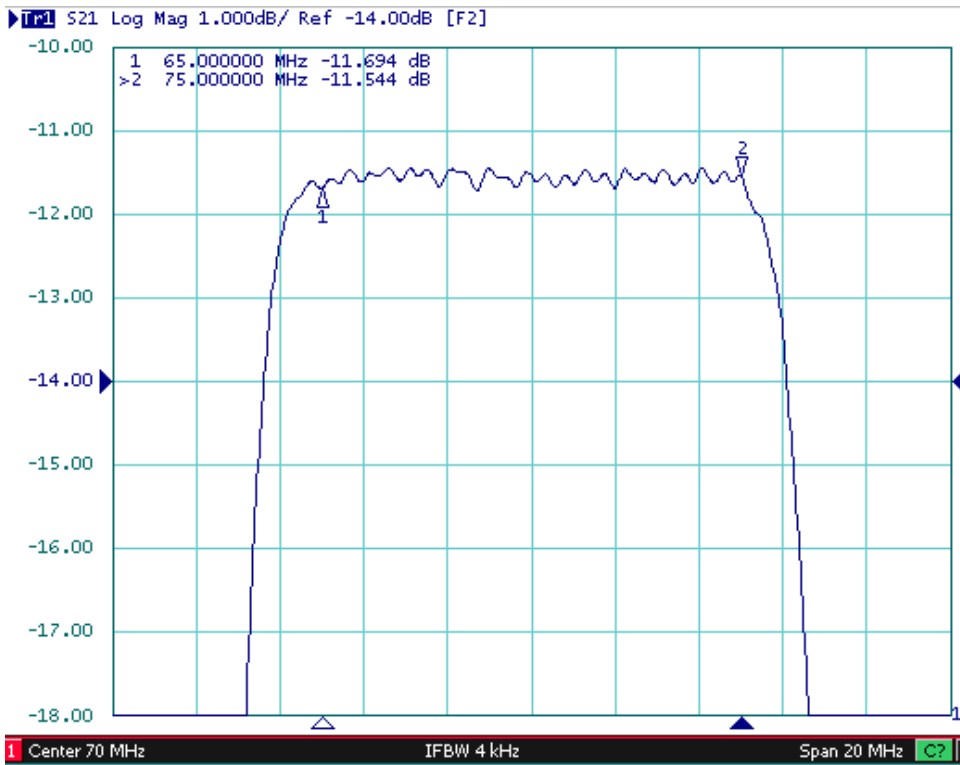
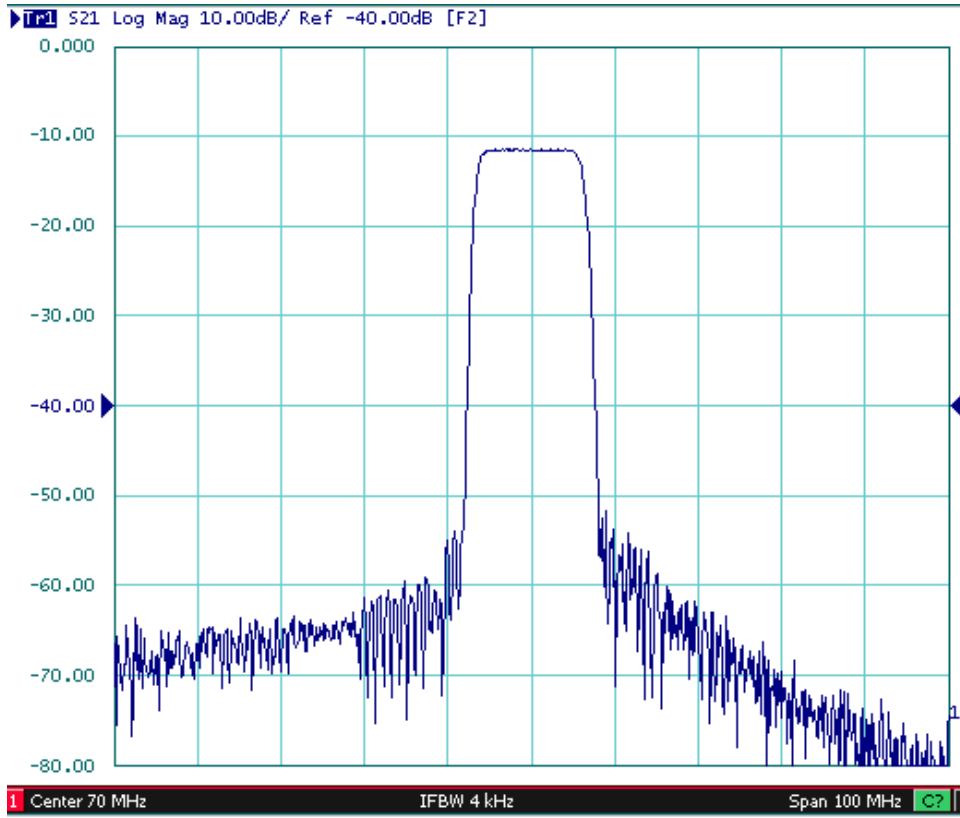


**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

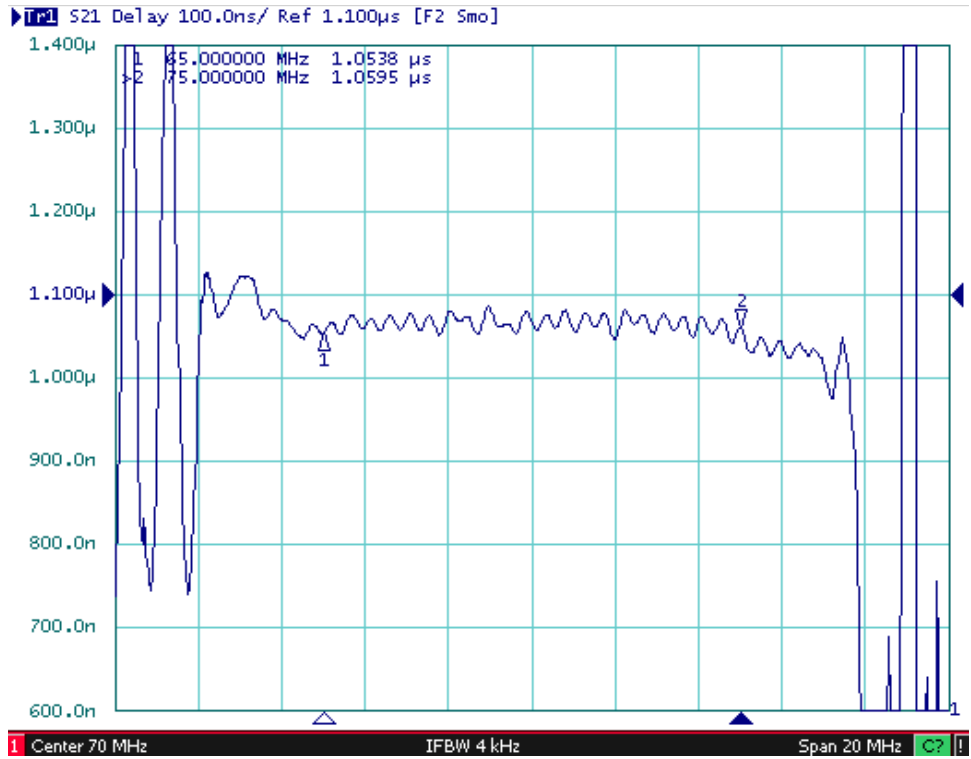
**NOTES:**

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

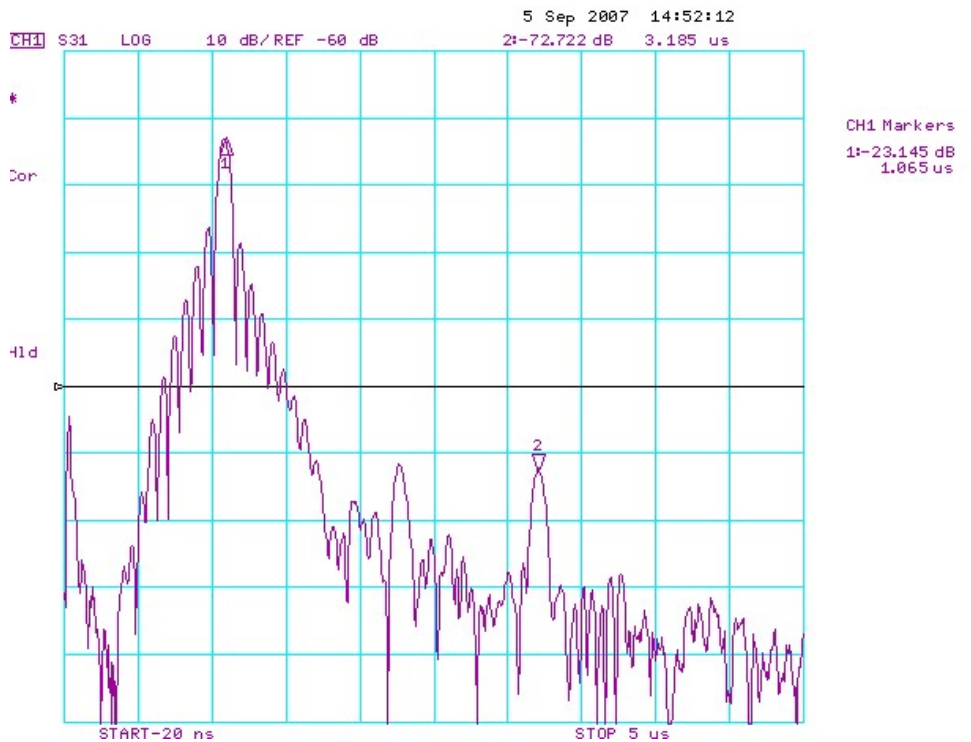
# Filter Frequency Response Plots



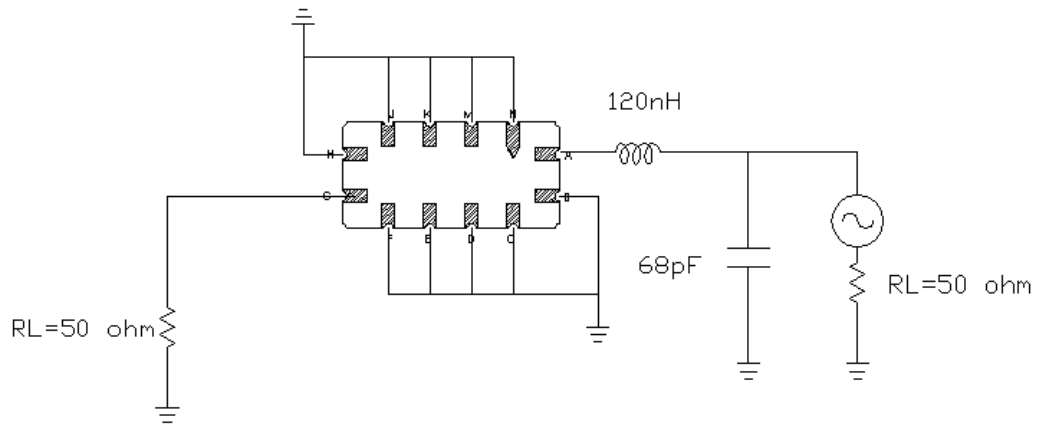
# Filter Group Delay Plot



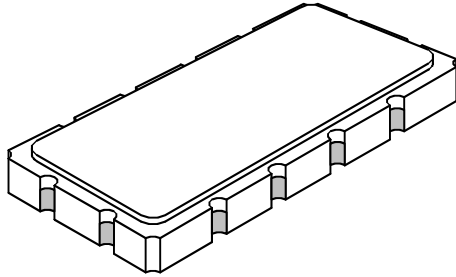
# Filter Time Domain Plot



## Typical Tuning Component Values



## Ceramic Surface-mount 12-Terminal Case 13.3 x 6.5 mm Nominal Footprint



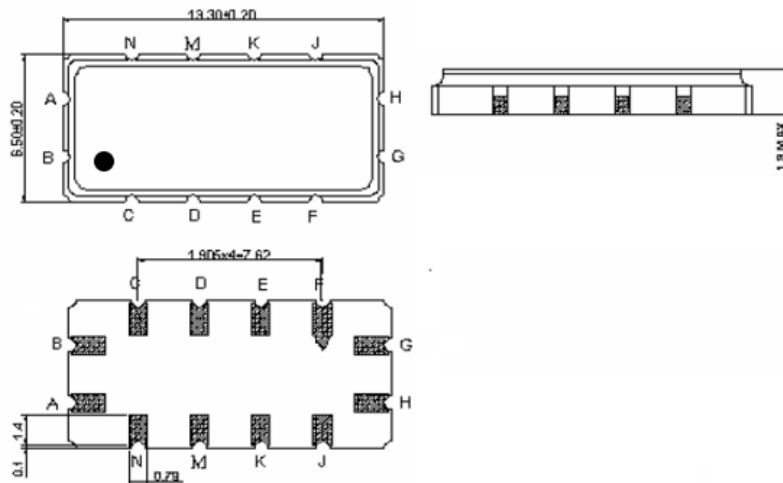
### Case Material

Materials	
Solder Pad Plating	0.3 to 1.0 $\mu\text{m}$ Gold over 1.27 to 8.89 $\mu\text{m}$ Nickel
Lid Plating	2.0 to 3.0 $\mu\text{m}$ Nickel
Body	$\text{Al}_2\text{O}_3$ Ceramic

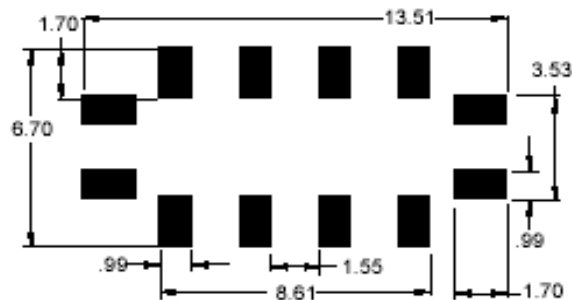
### Electrical Connections

Connection	Terminals
Input	A
Output	G
Case Ground	All others

### Case Outline Drawing



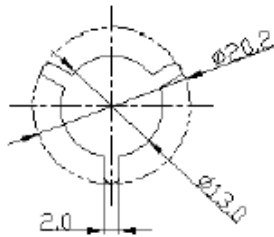
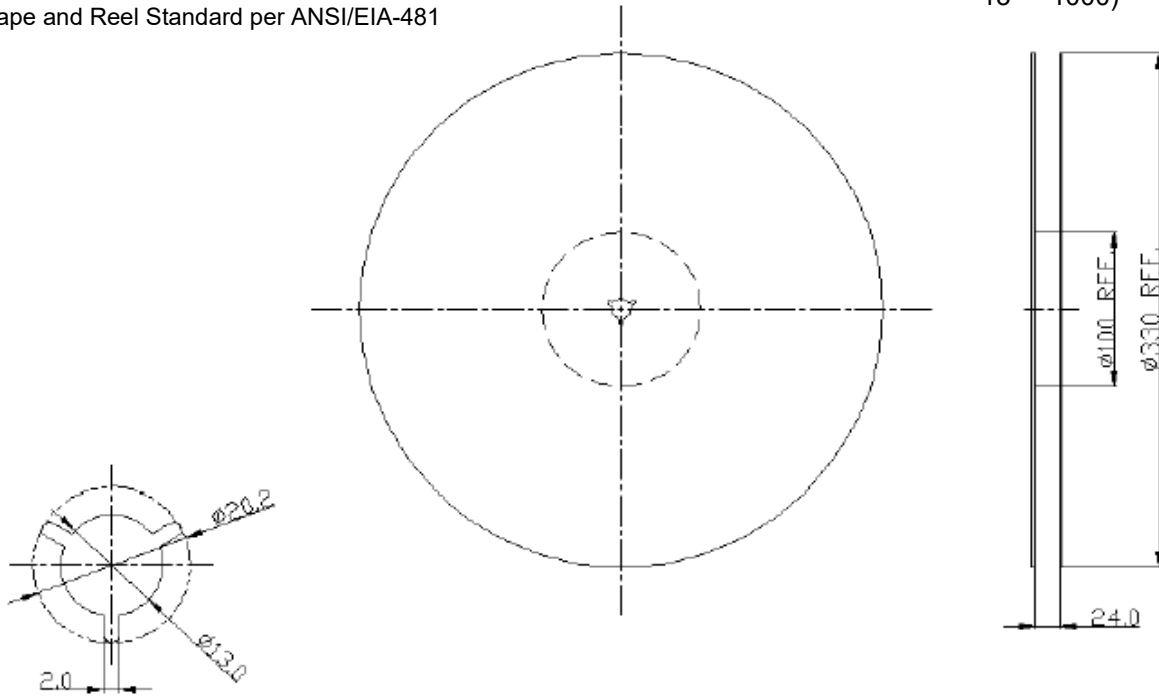
### PCB Pad Layout



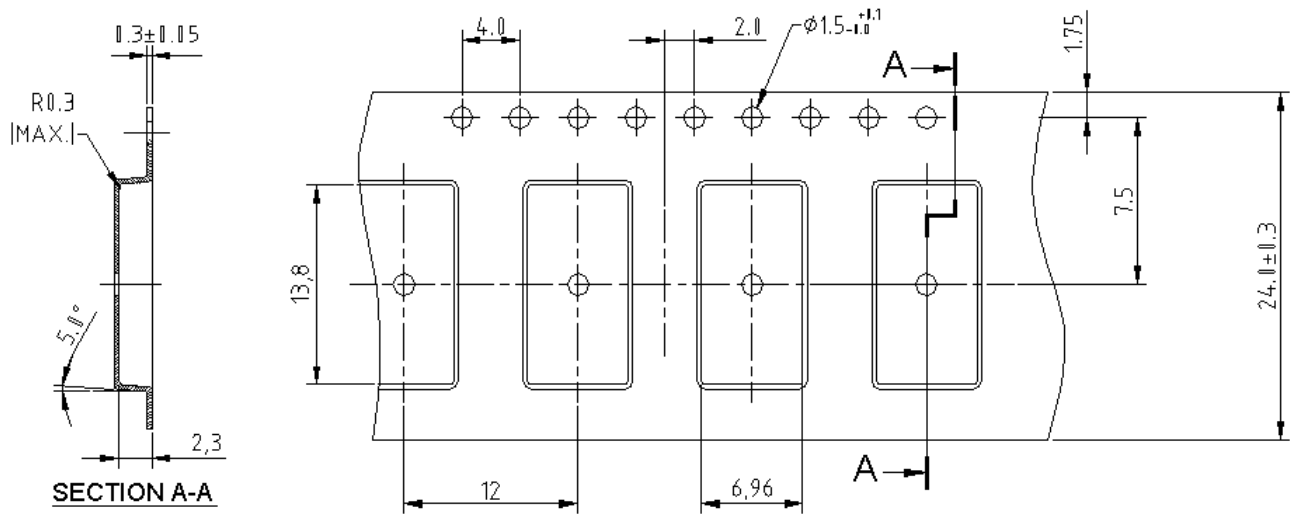
## Tape and Reel Specifications

Reel Count:  
 7" = 500  
 13" = 1000)

Tape and Reel Standard per ANSI/EIA-481



## 13.3X6.5



## Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

